

EPICLON[®] EXA-4850-150

Liquid high-performance epoxy resin

Advantages

1. Flexible skeleton introduced by unique bond (Molecular structure)
2. Liquid resin with easy operation (Resin characteristics)
3. Extremely excellent flexibility & toughness (Cured resin performance)
4. Outstanding high adhesive (Cured resin performance)
5. Greatly small curing shrinkage (Cured resin performance)

Applications

Semiconductor

Liquid encapsulant (Under-fill , Glob top)

Conductive paste (Die-attach paste , Anisotropic Conductive)

Semiconductor package materials (Build-up , Adhesive)

Circuit Board

Laminates (FR-4/FR-5/CEM)

Flexible circuit board (Adhesive to copper foil and cover lay)

Build up (Dry film , Adhesive copper foil)

Solder mask (Liquid type , Dry film)

Others

Composite materials (Glass or carbon fiber reinforced composite)

Adhesive (Industrial materials , Civil construction , Electronics materials)

Coating (Industrial coating , Civil construction)

Typical properties*

Appearance	Yellowish Clear Liquid
Alien substances	None
Epoxy equivalent, g/eq	440
Viscosity, mPa.s	16,000
Hydrolyzable Cl content, wt ppm	40

* Typical properties; not to be construed as specifications.

Storage

EPICLON[®] EXA-4850-150 has a shelf-life of at least 6 month if it is stored in a cool, dry area.

Read The Material Safety Data Sheet Before Handling, Storing or Using This product.

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Items mentioned in this information are for customers' reference and limited to certain examples although they are based on the most reliable data obtained by our company. It is hoped that customers make the best use of these products after careful examination.

<http://www.dic.co.jp/en/products/epoxy/index.html>

DIC Corporation